Title (en)

Assembly with at least one semiconductor module and a transport package

Title (de)

Anordnung mit mindestens einem Leistungshalbleitermodul und mit einer Transportverpackung

Title (fr)

Agencement doté d'au moins un module semi-conducteur de puissance et d'un emballage de transport

Publication

EP 2348804 B1 20130619 (DE)

Application

EP 10192495 A 20101125

Priority

DE 102010005048 A 20100120

Abstract (en)

[origin: EP2348804A1] The arrangement (1,1') has a transport packaging (2) which comprises a cover layer (10), an intermediate layer (20) with a recess (230), and a cover foil. The cover layer is formed with a main surface (100) in laminar manner, where the main surface faces a power semiconductor module (5). The cover foil covers a portion of the power semiconductor module. The cover foil is connected with a main surface (200) of the intermediate layer.

IPC 8 full level

H05K 13/00 (2006.01); **B65D 75/32** (2006.01); **B65D 75/36** (2006.01)

CPC (source: EP KR US)

B65D 75/327 (2013.01 - EP KR US); **B65D 75/367** (2013.01 - EP KR US); **B65D 81/02** (2013.01 - KR); **B65D 85/30** (2013.01 - KR); B65D 2575/3245 (2013.01 - EP KR US); B65D 2585/86 (2013.01 - KR)

Designated contracting state (EPC)

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DOCDB simple family (publication)

EP 2348804 A1 20110727; **EP 2348804 B1 20130619**; CN 102145795 A 20110810; CN 102145795 B 20150819; DE 102010005048 A1 20110721; JP 2011148555 A 20110804; JP 5732260 B2 20150610; KR 101784518 B1 20171011; KR 20110085870 A 20110727; US 2011203967 A1 20110825; US 8405195 B2 20130326

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EP 10192495 A 20101125; CN 201110025019 A 20110120; DE 102010005048 A 20100120; JP 2011005745 A 20110114; KR 20100137809 A 20101229; US 201113010637 A 20110120